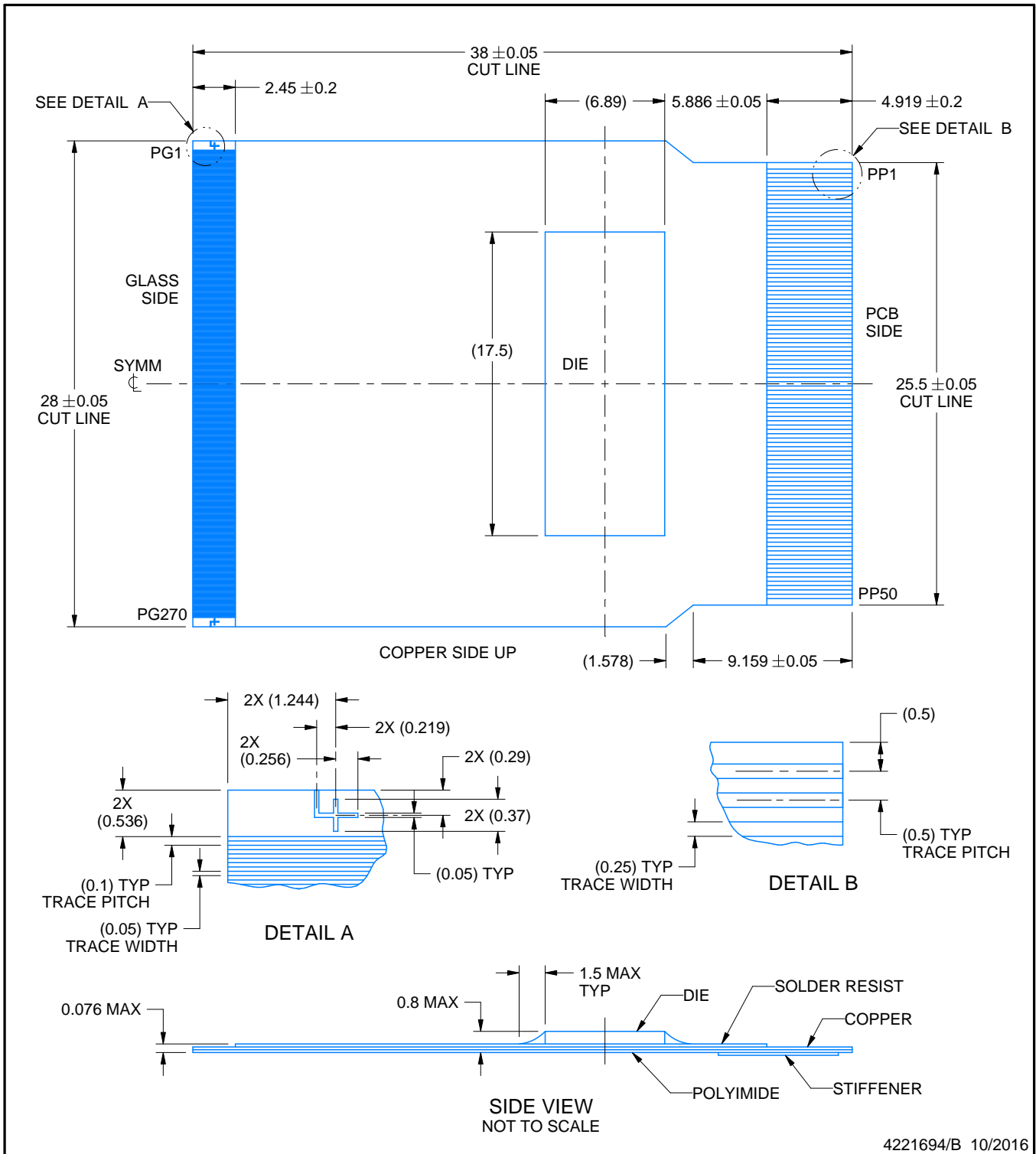


PACKAGE OUTLINE

TDU0320A

COF - 0.8 mm max height

CHIP ON FLEX



4221694/B 10/2016

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Flip chip application only.

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